AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) Electrospray source having a structure, comprising:

at least one flat and thin tip in cantilever in relation to the rest of the structure, said tip being provided with a capillary slot formed through ~~the~~ a complete thickness of the tip and which ends up at ~~the~~ an end of the tip to form ~~the~~ an ejection orifice of the electrospray source, the source comprising means of supplying the capillary slot with liquid to be nebulised and means of applying an electrospray voltage to said liquid.

2. (Previously Presented) Electrospray source according to claim 1, wherein the supply means comprise at least one reservoir in fluidic communication with the capillary slot.

3. (Previously Presented) Electrospray source according to claim 1, wherein the structure comprises a support and a wafer integral with the support and in which a part constitutes said tip.

4. (Previously Presented) Electrospray source according to claim 3, wherein the supply means comprise a reservoir constituted by a recess formed in said wafer and in fluidic communication with the capillary slot.

5. (Previously Presented) Electrospray source according to claim 1, wherein the means of applying an electrospray voltage comprise at least one electrode arranged so as to be in contact with said liquid to be nebulised.

6. (Previously Presented) Electrospray source according to claim 3, wherein the means of applying an electrospray voltage comprise the support, at least partially electrically conductive, and/or the wafer at least partially electrically conductive.

7. (Previously Presented) Electrospray source according to claim 1, wherein the means of applying an electrospray voltage comprise an electrically conductive wire arranged in order to be able to be in contact with said liquid to be nebulised.

8. (Previously Presented) Electrospray source according to claim 1, wherein the supply means comprise a capillary tube.

9. (Previously Presented) Electrospray source according to claim 1, wherein the supply means comprise a channel formed in a microsystem supporting said structure and in fluidic communication with the capillary slot.

10. (Previously Presented) Electrospray source according to claim 3, wherein the wafer has a surface hydrophobic to the liquid to be nebulised.

11. (Currently Amended) Method of manufacturing a structure being an electrospray source, comprising:

- the formation of a support from a substrate,

- the formation of a wafer having a part constituting a flat and thin tip, said tip being provided with a capillary slot, to convey a liquid to be nebulised, formed in **[[**the**]]** a complete thickness of the tip and which ends up **[[**the**]]** at an end of the tip,

- making said wafer integral on the support, the tip being in cantilever in relation to the support.

12. (Previously Presented) Method according to claim 11, wherein it comprises the following steps:

- the provision of a substrate to form the support,

- the delimitation of the support by means of trenches etched in the substrate,

- the deposition, on a zone of the substrate corresponding to the future tip of the structure, of sacrificial material according to a determined thickness,

- the deposition of the wafer on the support delimited in the substrate, the tip of the wafer being situated on the sacrificial material,

- the elimination of the sacrificial material,

- the detachment of the support in relation to the substrate by cleavage at the level of said trenches.

13. (Previously Presented) Method according to claim 12, wherein the step of deposition of the wafer is a deposition of a wafer comprising a recess in fluidic communication with the capillary slot in order to constitute a reservoir.

14. (Previously Presented) Method according to claim 12, wherein it further comprises a step of depositing at least one electrode intended to assure an electrical contact with the liquid to be nebulised.

15. - 18 (Canceled)

19. (Previously Presented) Ionization of a liquid by electrospraying the liquid with the electrospray source of claim 1, and analyzing the changed liquid by mass spectrometry.

20. (Previously Presented) Producing drops of liquid of a calibrated or controlled size by electrospraying a liquid using the electrospray source of claim 1.

21. (Previously Presented) Carrying out molecular writing with chemical compounds by electrospraying chemical compounds using the electrospray source of claim 1.

22. (Previously Presented) Electrospraying a liquid using the electrospray source of claim 1 to define the electrical junction potential of a device in fluidic continu ity.